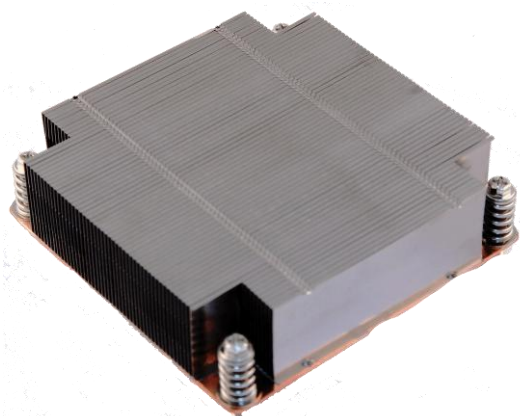




VEL-00008-N1-GP



Application

LGA 1366/1356 (Socket B/B2) M3

Test result:

	130W	150W
Flow (CFM)	Rca (°C/W)	Rca (°C/W)
10	0.2529	0.2626
15	0.2031	0.2109
16	0.199	0.2043
20	0.1796	0.1821
25	0.1638	0.1687
30	0.1541	0.1583
35	0.1472	0.1491
40	0.1423	0.1423
45	0.1374	0.1383
50	0.1343	0.1353

Safety

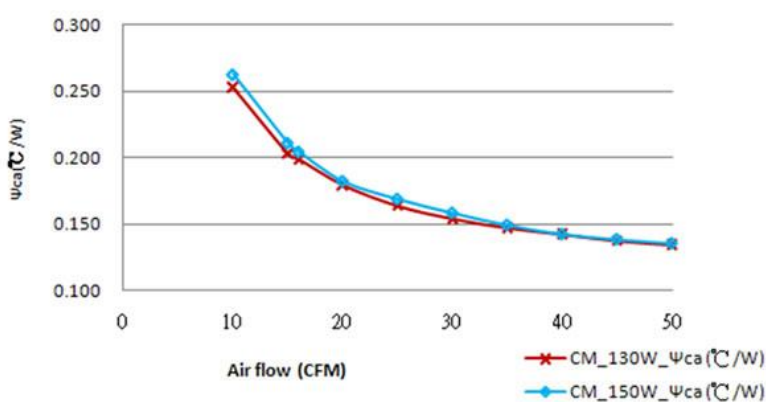
Thermal and Mechanical Spec

Thermal performance for 130W/150W CPU

HSK Assembly Weight: 205 g

CPU Loading: 65 lbf

Performance Curve



Component Specifications

Application System 1U Form Factor Passive Solution

Material Aluminum Fin + Vapor Chamber Base

Dimension 90L × 90W × 26.5H mm

Fin Thick=0.2mm, Pitch=1.38mm, 66 fin

Thermal interface
Material Shin Etsu 7783 (36 × 36 mm)

*All readings are typical values at rated voltage.

*Specifications are subjected to change without notice.

